



**DEFENSE LOGISTICS AGENCY**  
 LAND AND MARITIME  
 POST OFFICE BOX 3990  
 COLUMBUS, OH 43218-3990

April 15, 2011

Mr. Dave Alderman  
 American Standard Circuits  
 RF Division  
 475 Industrial Drive  
 West Chicago, IL 60185

Dear Mr. Alderman:

RE: Notification of Qualification, MIL-PRF-31032B, FSC 5998; VQ (VQE-11-022358)

Qualification of your products is granted under the current issue of the specification as a result of successful qualification testing to Department of Defense Performance Specification MIL-PRF-31032, Printed Circuit Board/Printed Wiring Board, and associated specifications MIL-PRF-31032/1 and MIL-PRF-31032/2. The capabilities indicated below shall be listed on Qualified Manufacturers List QML-31032. The effective date of this qualification is April 15, 2011.

<b>MANUFACTURER NAME &amp; ADDRESS</b>  American Standard Circuits RF Division 475 Industrial Drive West Chicago, IL 60185	<b>PLANT LOCATION</b>  American Standard Circuits RF Division 475 Industrial Drive West Chicago, IL 60185	<b>CAGE CODE: 4AA34</b>  PHONE #: (603) 639-5438 FAX #: (603) 293-1240 EMAIL: sales@asc-i.com																														
<b>CAPABILITIES BY TECHNOLOGY / ASSOCIATED SPECIFICATION:</b>		<b>QUALIFICATION LETTER:</b>																														
MIL-PRF-31032/1, MIL-PRF-31032/2  <table border="0"> <tr><td>Panel Size</td><td>12" X 18" (max)</td></tr> <tr><td>Max. Board Thickness</td><td>0.125"</td></tr> <tr><td>Max / Min Plated Hole Size</td><td>0.052" / 0.020" (after drill)</td></tr> <tr><td>Max Plated Hole Size</td><td>0.125" (mounting)</td></tr> <tr><td>Aspect Ratio</td><td>5:1</td></tr> <tr><td>Max. Number of Layers</td><td>10</td></tr> <tr><td>Min. Conductor Width</td><td>0.004"</td></tr> <tr><td>Min. Conductor Spacing</td><td>0.004" +/- 10%</td></tr> <tr><td>Part Mounting</td><td>SM, THM, MIX</td></tr> <tr><td>Base Material</td><td>GI (Woven E-Glass, Polyimide resin)</td></tr> <tr><td>Finish System</td><td>HASL, Electrolytic Ni/Hard Au, Immersion Ag</td></tr> <tr><td>Hole Preparation</td><td>Plasma Desmear, Permanganate Desmear</td></tr> <tr><td>Copper Plating</td><td>Acid Copper (DC Plate)</td></tr> <tr><td>Hole Wall Conductive Coating</td><td>Electroless Copper</td></tr> <tr><td>Solder Resist</td><td>Liquid Photoimagable</td></tr> </table>		Panel Size	12" X 18" (max)	Max. Board Thickness	0.125"	Max / Min Plated Hole Size	0.052" / 0.020" (after drill)	Max Plated Hole Size	0.125" (mounting)	Aspect Ratio	5:1	Max. Number of Layers	10	Min. Conductor Width	0.004"	Min. Conductor Spacing	0.004" +/- 10%	Part Mounting	SM, THM, MIX	Base Material	GI (Woven E-Glass, Polyimide resin)	Finish System	HASL, Electrolytic Ni/Hard Au, Immersion Ag	Hole Preparation	Plasma Desmear, Permanganate Desmear	Copper Plating	Acid Copper (DC Plate)	Hole Wall Conductive Coating	Electroless Copper	Solder Resist	Liquid Photoimagable	VQE-11-022358
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Test report number 31032-2960-10 has been assigned to your test data. This qualification is based on your MIL-PRF-31032 certification and is subject to the conditions stated below:

1. A listing on the Qualified Manufacturers List (QML) does not guarantee acceptance of the product(s) in any future purchase.
2. QML listing does not constitute a waiver of any requirements of the specification or of the provisions of any contract.
3. Advertising of qualification information is permitted. Permission to use such information for advertising or publicity purposes is granted provided that such publicity or advertising does not state or imply that the product(s) is the only product of that type qualified or that the Department of Defense in any way recommends or endorses the manufacturer's product.
4. The listing applies only to products produced in the plant(s) specified in this letter of notification of qualification and applies to future amendments or revisions of the specification, unless otherwise notified.
5. The listing applies only to materials and manufacturing construction techniques identical to or covered by that (those) qualified. The qualifying activity must be advised in advance of any change to the materials and manufacturing construction techniques. Failure to notify the qualifying activity of any change to the materials and manufacturing construction techniques is cause for removal from the QML.

Because we are held responsible for the accuracy and currency of this QML, please let us know if your company discontinues production utilizing these materials or processes. If you have any questions, please contact Mr. Lowell Sherman, (614) 692-0627 or [vqe.ls@dla.mil](mailto:vqe.ls@dla.mil).

Sincerely,

/SIGNED/

JOSEPH GEMPERLINE  
Chief  
Sourcing and Qualifications Division